



A circuit board having a lateral conductive pattern and shielded regions as well as a method of manufacturing such a board
Abstract

A circuit board with a lateral conductive pattern and shielded regions comprises a first contour cut laminate of a substrate (1) having a conductive pattern of signal conductors (2) and ground conductors (3) on one side and a copper foil (4) on the other side, covering the entire side. This laminate is laminated with the side provided with the conductive pattern to a second laminate also comprising a contour cut substrate (6) and a copper foil (7) provided on the substrate on the side opposite to the first laminate. Windows (8) are cut in the substrate of the second laminate and are etched away in the top copper foil (7) to enable mounting of components to the conductive pattern in the windows. A metal layer (10) is provided to electrically connect said foil (4) covering the entire other side of the first laminate with the ground conductors (3) of the conductive pattern and the foil (7) of the second laminate. In a method of manufacturing such a circuit board a first laminate of a substrate (1), covered on one side by a copper foil (4), is contour cut whereafter a second entirely covering copper foil is laminated to the second side of the substrate (1), and a conductive pattern of signal conductors (2) and ground conductors (3) is etched in the second copper foil. The second substrate (6) is also contour cut and is laminated to a copper foil (7), whereafter a window is etched in the copper foil, corresponding to the window (8) cut in the substrate (6). The second laminate thus formed is adjusted in regard of the pattern to the first laminate and is adhesively secured thereto, the side of the second laminate covered by the copper foil (7) turned away from the side of the first laminate provided with the conductive pattern. A metal layer (10) is thereafter applied to the surface of the first laminate facing away from the side having the conductive pattern and the lateral edges to electrically connect said surface, the ground conductors of the conductive pattern and the foil (7) on the second substrate, whereafter components are mounted in the windows (8) in the second laminate to the conductive pattern.

Figure 2